1.0AMP Surface Mount Rectifiers









### **Features**

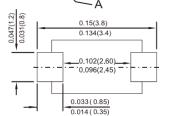
- ♦ UL Recognized File # E-326243
- ♦ For surface mounted application
- ♦ Glass passivated junction chip
- ♦ Low-Profile Package
- ♦ Ideal for automated placement
- ♦ Low power loss, high efficiency
- → High temperature soldering:
   260 ℃ /10 seconds at terminals
- ♦ Green compound with suffix "G" on packing code & prefix "G" on datecode
- ♦ Qualified as per AEC-Q101

# **Mechanical Data**

- ♦ Case: Sub SMA plastic case
- ♦ Terminal: Pure tin plated, lead free
- ♦ Polarity: Color band denotes cathode
- ♦ Packaging: 8mm / 12mm tape per EIA STD RS-481
- ♦ Weight: 0.0196 grams
- Marking code refer to below specified

# Cathode Band Cathode Band O.012(0.30) O.114(5.9) O.106(5.7) O.106(5.7) O.106(5.7) O.106(5.7) O.106(5.7)

Sub SMA





# **Dimensions in inches and (millimeters)**

## Marking Diagram

1XLGYM

1XL = Specific Device Code G = Green Compound Y = Year

M = Work Month

# **Maximum Ratings and Electrical Characteristics**

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	S1AL	S1BL	S1DL	S1GL	S1JL	S1KL	S1ML	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T <sub>L</sub> =110℃ @Ttp=75℃ 20ms Square pulse	I <sub>F(AV)</sub>	1.0 1.5							А
Peak Forward Surge Current, 8.3 ms Single Half Sinewave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	30							Α
Maximum Instantaneous Forward Voltage (Note 1) @ 1 A	V <sub>F</sub>	1.1							V
	I <sub>R</sub>	5 50						uA uA	
Typical Junction Capacitance (Note 2)	Cj	9						pF	
Typical Reverse Recovery Time (Note 3)	Trr	1.8						uS	
Typical Thermal Resistance (Note 4)	$R_{ heta JA}$	25 30 85 85				-	°C/W		
Operating Temperature Range	TJ	- 55 to + 175						°С	
Storage Temperature Range	T <sub>STG</sub>	- 55 to + 175							οС

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

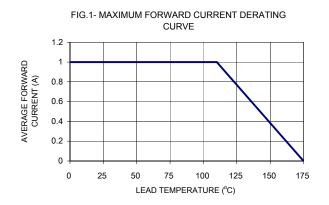
Note 2: Measured at 1 MHz and Applied VR=4.0 Volts.

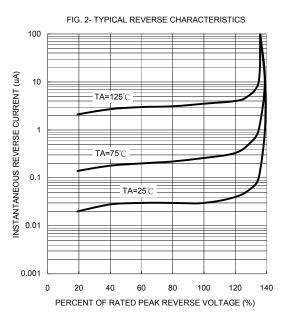
Note 3: Reverse Recovery Test Conditions:  $I_F$ =0.5A,  $I_R$ =1.0A,  $I_{RR}$ =0.25A

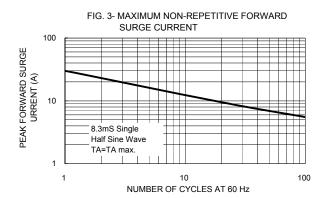
Note 4: Measured on P.C. Board with 0.2" x 0.2" (5.0mm x 5.0mm) Copper Pad Areas.



# RATINGS AND CHARACTERISTIC CURVES (S1AL THRU S1ML)







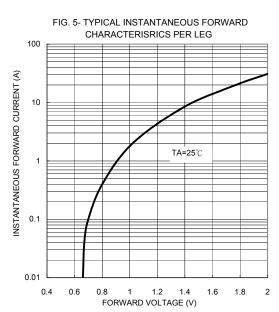
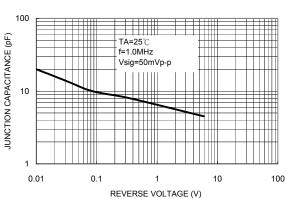


FIG. 4- TYPICAL JUNCTION CAPACITANCE



Version:I11